MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
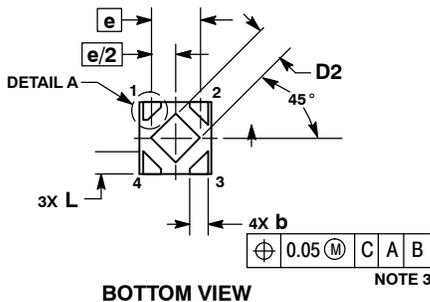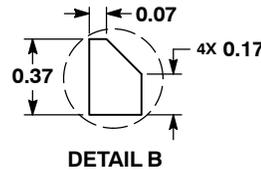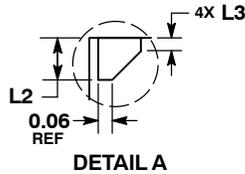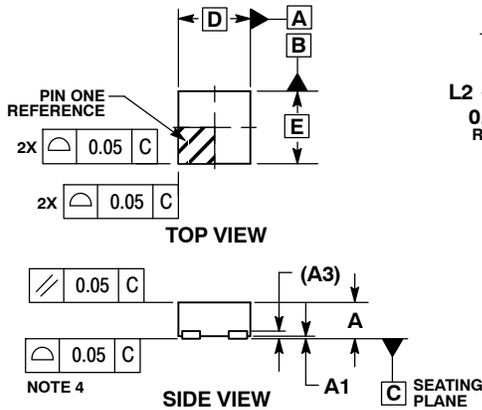
ON Semiconductor®

XDFN4 0.8x0.8, 0.48P
CASE 711AB–01
ISSUE O

DATE 21 OCT 2010

SCALE 4:1

1

TOP VIEW

PIN ONE REFERENCE

2X ◠ 0.05 C

2X ◠ 0.05 C

DETAIL A

4X **L3**

L2

0.06 REF

SIDE VIEW

// 0.05 C

◠ 0.05 C

NOTE 4

(A3)

A

A1

C SEATING PLANE

DETAIL B

0.07

0.37

4X **0.17**

BOTTOM VIEW

DETAIL A

e

e/2

1   2

45°

D2

4   3

3X L

4X b

⊕ 0.05 Ⓜ C A B

NOTE 3

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

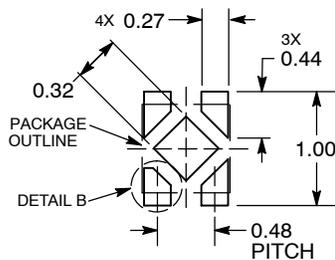| DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
A3	0.10 REF	
b	0.17	0.27
D	0.80 BSC	
D2	0.20	0.30
E	0.80 BSC	
e	0.48 BSC	
L	0.23	0.33
L2	0.17	0.27
L3	0.01	0.11

GENERIC MARKING DIAGRAM*

XM
M

1 ○
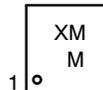
X   = Specific Device Code
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*

4X 0.27

0.32

PACKAGE OUTLINE

DETAIL B

3X 0.44

1.00

0.48 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON53252E	
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN4, 0.8X0.8, 0.48P	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY B. LOFTS.	21 OCT 2010